ABSTRACT

TAPE SUBSTRATES WITH MOLD GATE SUPPORT STRUCTURES THAT ARE COPLANAR WITH CONDUCTIVE TRACES THEREOF AND ASSOCIATED METHODS

A mold gate of a tape substrate includes an aperture formed in the flexible dielectric film of the tape substrate and a support element which is carried by a surface of the flexible dielectric film, is substantially coplanar with conductive traces carried by the flexible dielectric film, and may be formed from the same material as the conductive traces. The aperture of the mold gate may be formed by die cutting or etching processes. The support element of the mold gate may be fabricated by patterning a conductive film and formed at substantially the same time as the conductive traces of the tape substrate are formed. Packaging methods and degating methods that include use of the tape substrate are also within the scope of the present invention.

[FIG. 12]